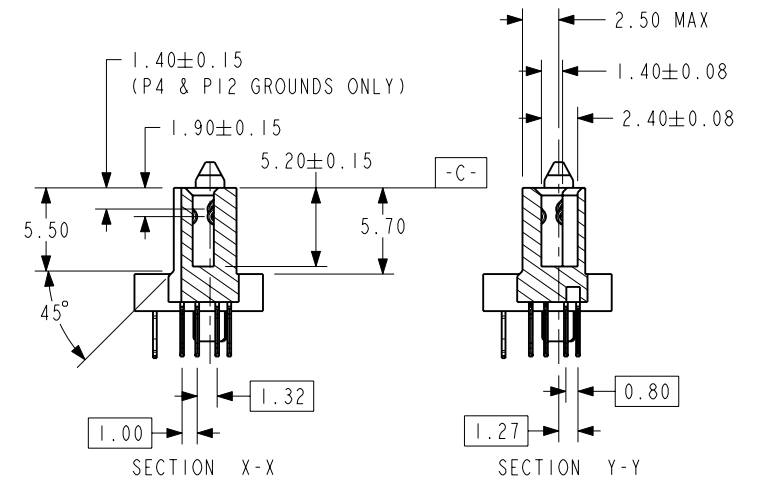
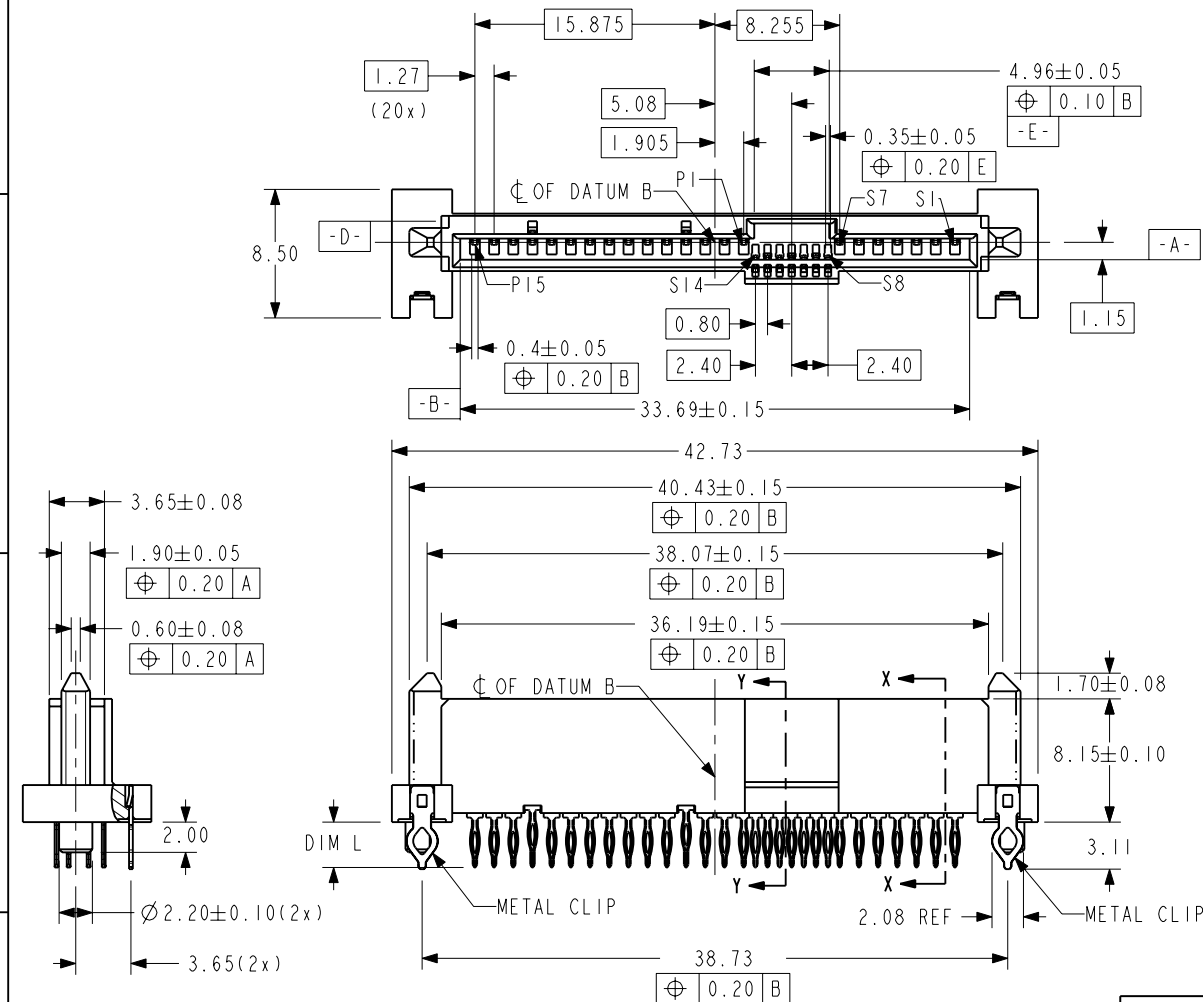


PRODUCT NO	DIM L	RECOMMENDED P.C. BOARD THICKNESS	METAL CLIP
10038064-001LF	2.70	1.40mm (0.055")/2.36mm (0.093")	YES
10038064-002LF	3.60	2.36mm (0.093")	
10038064-003LF	2.70	1.40mm (0.055")/2.36mm (0.093")	NO
10038064-004LF	3.60	2.36mm (0.093")	



www.fciconnect.com			surface ☒		tolerance std		projection 		MM 	
			TOLERANCES UNLESS OTHERWISE SPECIFIED							
Dr	YEO SS	2005-07-26	ANGULAR	LINEAR	0.X	±0.2	size	A4	Scale	2:1
Eng	KP TAY	2010-06-15			0.XX	±0.2				
Chr	KP TAY	2010-06-15			0.XXX	±0.2				
Appr	JOEY NG	2010-06-15	Product family			SAS	ECN S10-0127			
						Spec ref				
			title SAS RECEPTACLE PRESS FIT (WIDE BASE)			dwg no 10038064			Rev. D	
			catalog no -			CUSTOMER			sheet 1 of 2	

rev	ecn no	dr	date
A	S05-0043	SSYEO	2005-07-26
B	S05-0296	SSYEO	2005-10-19
C	S07-0256	WLC	2007-07-26
D	S10-0127	KPTAY	2010-06-15
-	-	-	-
-	-	-	-
-	-	-	-

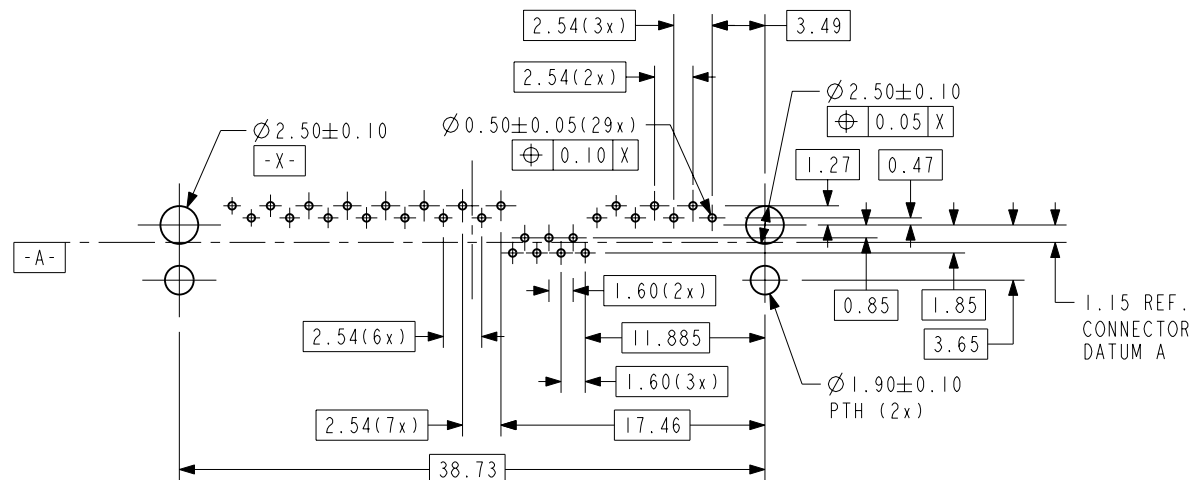
REV E - 2006-03-28

PDM: Rev:D

STATUS: Released

Printed: Dec 01, 2010

HOLE	A
HOLE DIAMETER AFTER PLATING	0.45-0.55 mm
DRILLED HOLE	0.58-0.62 mm
COPPER PLATING	25-50 μ m
Sn PLATING	5-15 μ m



RECOMMENDED PCB LAYOUT

NOTE:

1. MATERIAL:
 - A) HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL 94V-0
COLOUR: BLACK
 - B) TERMINAL; COPPER ALLOY
 - C) HOLD DOWN: COPPER ALLOY
- 2 FINISH (LEAD-FREE):
 - A) TERMINAL: 30 μ " Au PLATING (CONTACT POINT) OVER 50 μ " NICKEL
 - B) PRESSFIT TAIL: 20 μ " MIN - 60 μ " MAX Sn OVER 50 μ " NICKEL
 - C) HOLD DOWN: 50 μ " min Sn OVER 50 μ " NICKEL
- 3 PER SFF REV 1.4 EXCEPT 0.8mm PITCH BUMP AREA.
- 4 THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
- 5 THIS PRODUCT MEETS EUROPE UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- 6 PART NUMBERS ENDING IN "LF" MEANS FOR NOTE 5 LEAD FREE IDENTIFICATION. P/N XXXXXXXX-XXXLF IS EQUIVALENT TO PREVIOUS P/N XXXXXXXX-XXX.



title	SAS RECEPTACLE PRESS FIT (WIDE BASE)	dwg no	10038064	Rev.	D
catalog no	-	CUSTOMER	sheet 2 of 2		